MOSFETs Silicon P-Channel MOS (U-MOSVI)

TJ150F06M3L

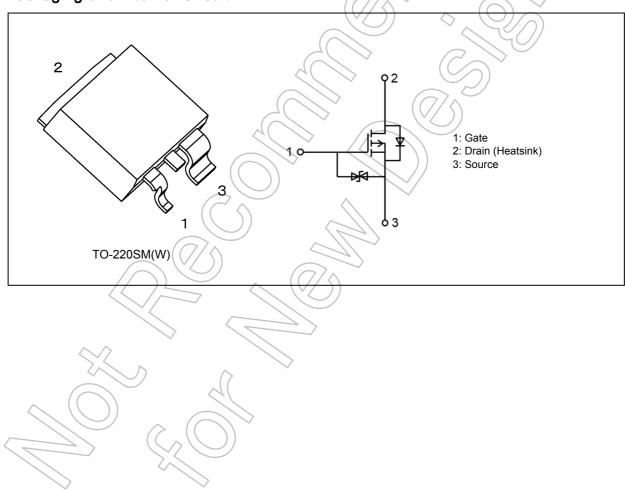


- Automotive
- Relay Drivers
- Motor Drivers

2. Features

- (1) AEC-Q101 qualified
- (2) Low drain-source on-resistance: $R_{DS(ON)} = 4.3 \text{ m}\Omega$ (typ.) ($V_{GS} = -10 \text{ V}$)
- (3) Low leakage current: $I_{DSS} = -10 \ \mu A \ (max) \ (V_{DS} = -60 \ V)$
- (4) Enhancement mode: $V_{th} = -2.0$ to -3.0 V ($V_{DS} = -10$ V, $I_D = -1$ mA)

3. Packaging and Internal Circuit



4. Absolute Maximum Ratings (Note) ($T_a = 25 \ ^{\circ}C$ unless otherwise specified)

Characteristics			Symbol	Rating	Unit
Drain-source voltage			V _{DSS}	-60	V
Gate-source voltage			V _{GSS}	-20/+10	
Drain current (DC)		(Note 1)	I _D	-150	А
Drain current (pulsed)		(Note 1)	I _{DP}	-450	
Power dissipation	(T _c = 25°C)		PD	300	W
Single-pulse avalanche energy		(Note 2)	E _{AS}	430	mJ
Avalanche current			I _{AR}	-150	А
Channel temperature		(Note 3)	T _{ch}) 175	°C
Storage temperature		(Note 3)	T _{stg}	-55 to 175	

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

5. Thermal Characteristics

Characteristics			Symbol	Max	Unit
Channel-to-case thermal resistance	$\langle \langle \rangle$	(\vee)	R _{th(ch-c)}	0.5	°C/W
			/		

Note 1: Ensure that the channel temperature does not exceed 175 °C.

Note 2: V_{DD} = -25 V, T_{ch} = 25°C (initial), L = 26 μ H, R_G = 25 Ω , I_{AR} = -150 A

Note 3: The definitions of the absolute maximum channel and storage temperatures are qualified per AEC-Q101.

Note: This transistor is sensitive to electrostatic discharge and should be handled with care.

6. Electrical Characteristics

6.1. Static Characteristics ($T_a = 25$ °C unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage current	I _{GSS}	V _{GS} = -16/+10 V, V _{DS} = 0 V	_	_	±10	μA
Drain cut-off current	I _{DSS}	V_{DS} = -60 V, V_{GS} = 0 V	Ľ	—	-10	
Drain-source breakdown voltage	V _{(BR)DSS}	I _D = -10 mA, V _{GS} = 0 V	-60		_	V
Drain-source breakdown voltage (Note 4)	V _{(BR)DSX}	I _D = -10 mA, V _{GS} = 10 V	-50	$\left \right\rangle$	_	
Gate threshold voltage	V _{th}	V _{DS} = -10 V, I _D = -1 mA	-2.0	2_	-3.0	
Drain-source on-resistance	R _{DS(ON)}	V_{GS} = -6 V, I_{D} = -75 A	γ	4.7	6.1	mΩ
		V _{GS} = -10 V, I _D = -75 A	$\supset \downarrow$	4.3	5.6	

Note 4: If a reverse bias is applied between gate and source, this device enters V_{(BR)DSX} mode. Note that the drainsource breakdown voltage is lowered in this mode.

6.2. Dynamic Characteristics ($T_a = 25$ °C unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Тур.	> Max	Unit
Input capacitance	C _{iss}	V _{DS} = -10 V, V _{GS} = 0 V, f = 1 MHz		12500) —	pF
Reverse transfer capacitance	C _{rss}		A	880	_	
Output capacitance	C _{oss}			1750		
Switching time (rise time)	t _r	See Fig. 6.2.1.	ZЭ)	15	_	ns
Switching time (turn-on time)	t _{on}		\sim	35	_	
Switching time (fall time)	t _f)) —	465	_	
Switching time (turn-off time)	t _{off}		_	1760	_	

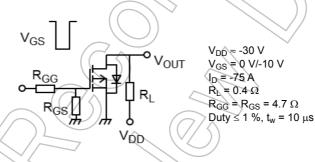


Fig. 6.2.1 Switching Time Test Circuit

6.3. Gate Charge Characteristics ($T_a = 25$ °C unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Total gate charge (gate-source plus gate-drain)	Qg	$V_{DD} \approx$ -48 V, V_{GS} = -10 V, I_D = -150 A	—	420	_	nC
Gate-source charge 1	Q _{gs1}		_	83	—	
Gate-drain charge	Q _{gd}			112	_	

6.4. Source-Drain Characteristics ($T_a = 25$ °C unless otherwise specified)

Characteristics		Symbol	Test Condition	Min	Тур.	Max	Unit
Reverse drain current (DC)	(Note 5)	I _{DR}	—	_	_	-150	А
Reverse drain current (pulsed)	(Note 5)	I _{DRP}		_	_	-450	
Diode forward voltage		V _{DSF}	I _{DR} = -75 A, V _{GS} = 0 V	_	_	1.5	V
Reverse recovery time		t _{rr}	I _{DR} = -150 A, V _{GS} = 0 V	_	63	_	ns
Reverse recovery charge		Q _{rr}	dl _{DR} /dt = 50 A/µs		60		nC

Note 5: Ensure that the channel temperature does not exceed 175 °C.

7. Marking (Note)

Part No. (or abbreviation code) 3L Lot No.
Fig. 7.1 Marking
A line under a Lot No. identifies the indication of product Labels. Not underlined: [[Pb]]/INCLUDES > MCV Underlined: [[G]]/RoHS COMPATIBLE or [[G]]/RoHS [[Pb]] Please contact your TOSHIBA sales representative for details as to environmental matters such as the RoHS compatibility of Product. The RoHS is the Directive 2011/65/EU of the European Parliament and of the Council of 8 June 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment,

8. Moisture-Proof Packing

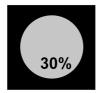
This device is packed in a moisture-proof laminated aluminum bag.

8.1. Precautions for Transportation and Storage (Note)

- (1) Avoid excessive vibration during transportation.
- (2) Do not toss or drop the packed devices to avoid ripping of the bag.
- (3) After opening the moisture-proof bag, the devices should be assembled within two weeks in an environment of 5 °C to 30 °C and RH70 % or below. Perform reflow at most twice.
- (4) The moisture-proof bag may be stored unopened for up to 24 months at 5 °C to 30 °C and RH90 % or below.
- (5) If, upon opening the bag, the moisture indicator card shows humidity of 30 % or above (the color of the 30 % dot has changed from blue to pink) or the expiration date has passed, the devices should be baked as follows:

Baking conditions: 125 °C for 48 hours.

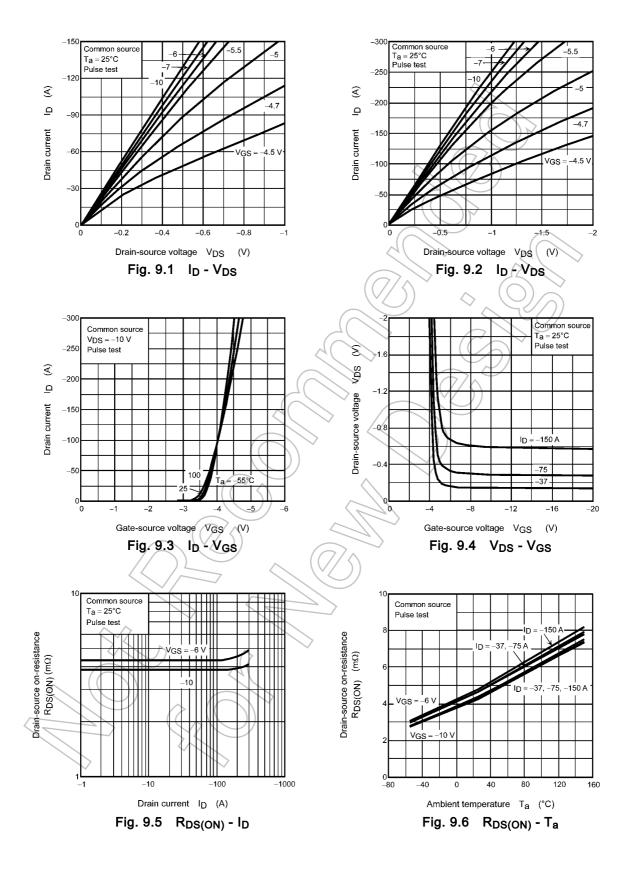
Note: Since the tape materials are not heat-proof, devices should be placed on either heat-proof trays or aluminum magazines when baking.



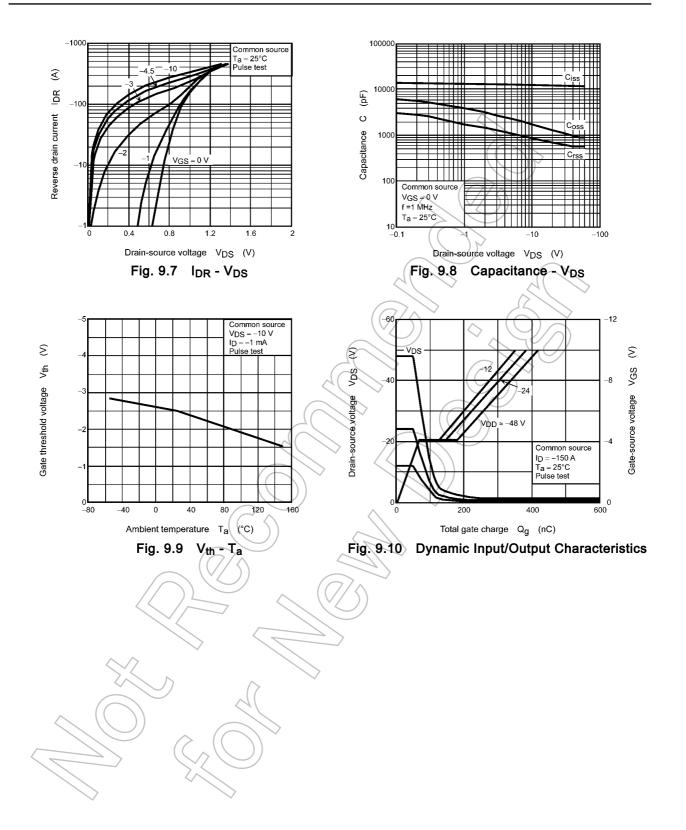
The humidity indicator shows an approximate ambient humidity at $25 \,^{\circ}$ C. If the ambient humidity is below 30 %, the color of all the indicator dots is blue. If, upon opening the bag, the color of the 30 % dot has changed from blue to pink, the devices should be baked before assembly.

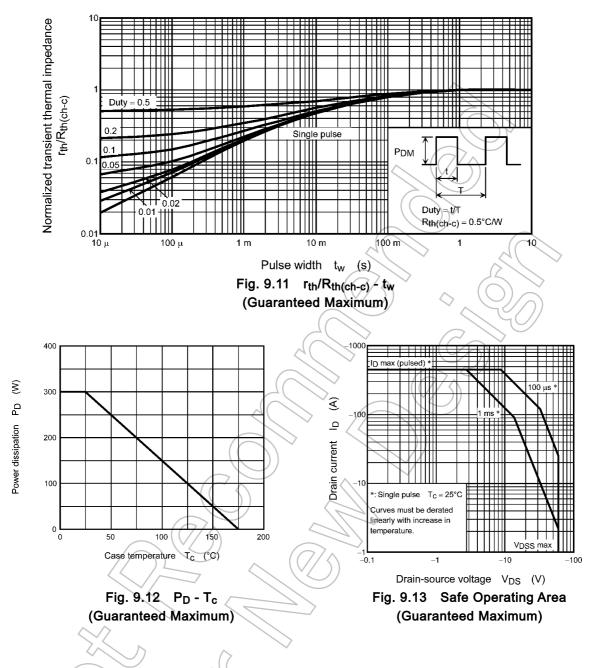
Fig. 8.1.1 Humidity Indicator

9. Characteristics Curves (Note)





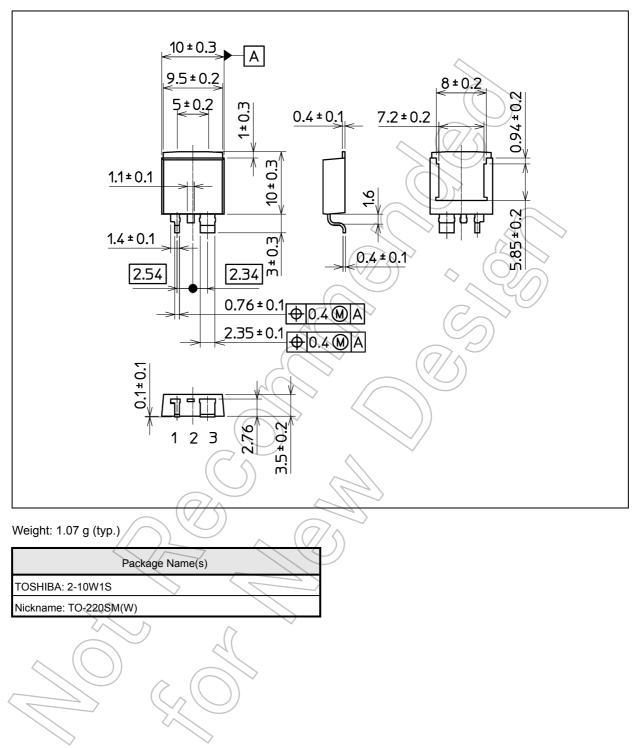




Note: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.

Package Dimensions

Unit: mm



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